

General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	RDS(ON)	ID
60V	4.6mΩ	100A

Features

- 60V, 100A, RDS(ON) = 4.6mΩ@VGS = 10V
- Improved dv/dt capability
- Fast switching
- Green Device Available

PPAK5X6 Pin Configuration



Applications

- PowerTools
- Load Switch
- LED applications
- Motor Drive Applications

Absolute Maximum Ratings T_c=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	60	V
V _{GS}	Gate-Source Voltage	±20	V
I _D	Drain Current – Continuous (T _c =25°C)	100	A
	Drain Current – Continuous (T _c =100°C)	63	A
I _{DM}	Drain Current – Pulsed ¹	400	A
EAS	Single Pulse Avalanche Energy ²	450	mJ
IAS	Single Pulse Avalanche Current ²	95	A
P _D	Power Dissipation (T _c =25°C)	142	W
	Power Dissipation – Derate above 25°C	1.14	W/°C
T _{STG}	Storage Temperature Range	-50 to 150	°C
T _J	Operating Junction Temperature Range	-50 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction to ambient	---	62	°C/W
R _{θJC}	Thermal Resistance Junction to Case	---	0.88	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	60	---	---	V
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=60\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{\text{DS}}=48\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA

On Characteristics

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=10\text{V}$, $I_D=20\text{A}$	---	3.8	4.6	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$, $I_D=10\text{A}$	---	4.2	5.5	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D = 250\mu\text{A}$	1	1.6	2.5	V
g_{fs}	Forward Transconductance	$V_{\text{DS}}=10\text{V}$, $I_D=3\text{A}$	---	25	---	S

Dynamic and switching Characteristics

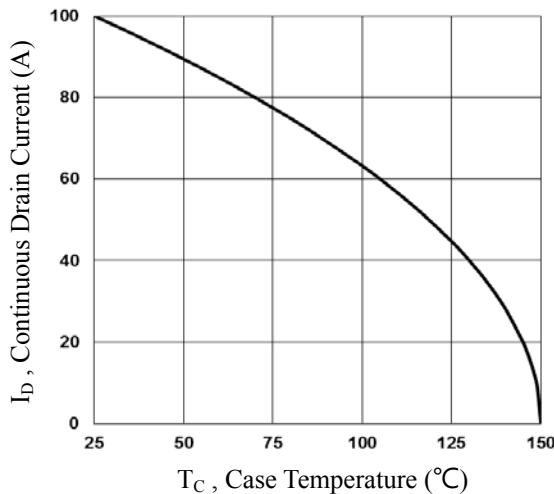
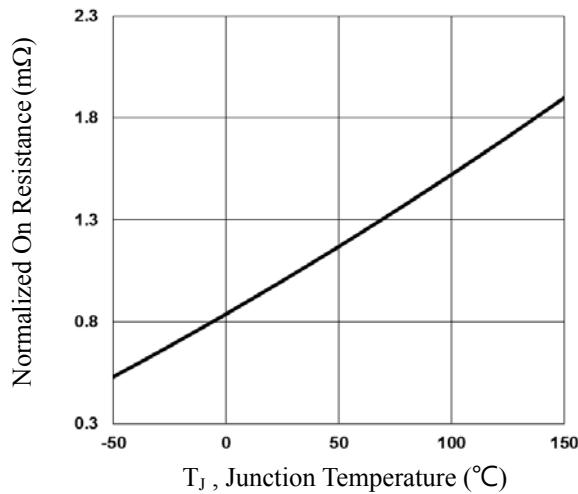
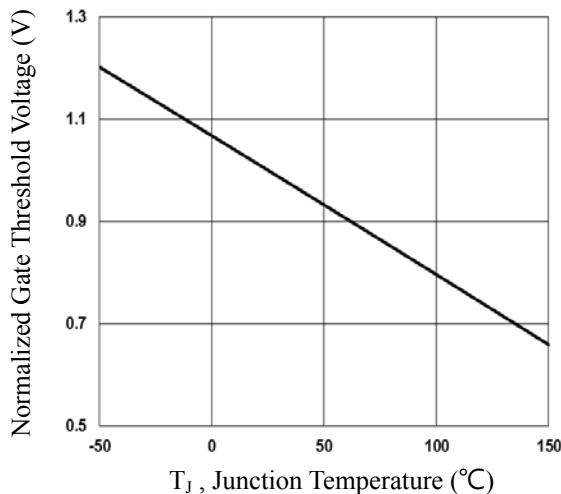
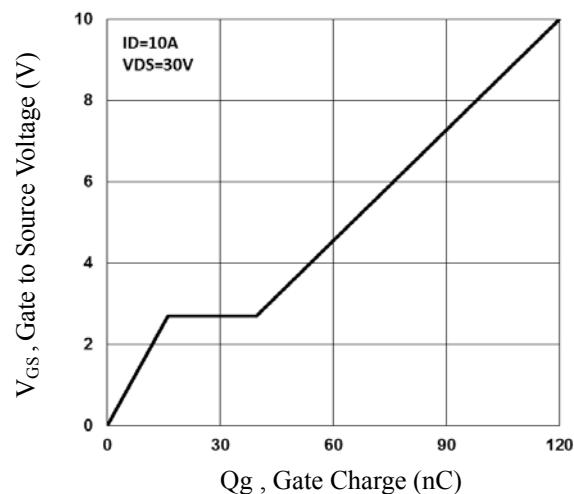
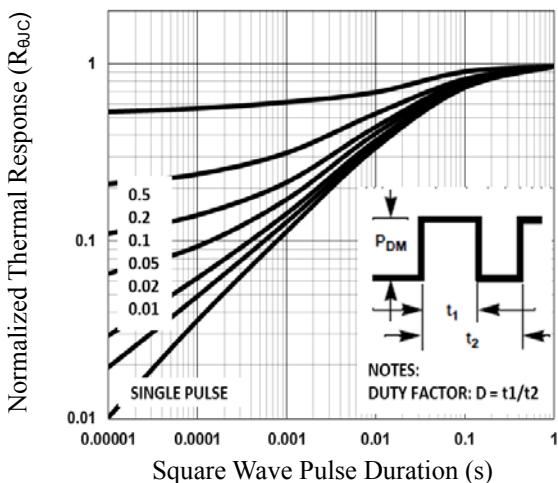
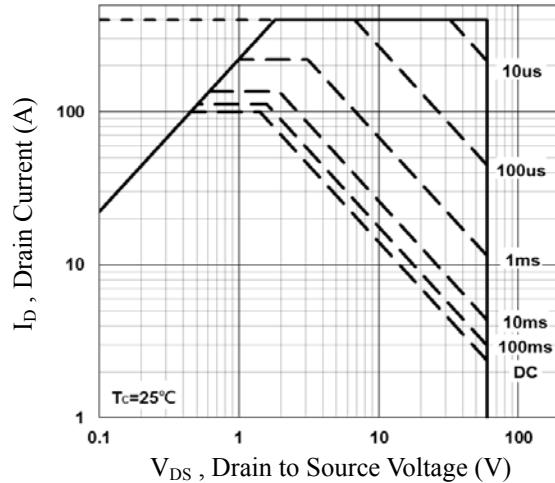
Q_g	Total Gate Charge ^{3,4}	$V_{\text{DS}}=30\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $I_D=10\text{A}$	---	58.2	116	nC
Q_{gs}	Gate-Source Charge ^{3,4}		---	16.2	32	
Q_{gd}	Gate-Drain Charge ^{3,4}		---	23.4	46	
$T_{\text{d(on)}}$	Turn-On Delay Time ^{3,4}	$V_{\text{DD}}=30\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=6\Omega$ $I_D=1\text{A}$	---	19.2	40	ns
T_r	Rise Time ^{3,4}		---	56.3	120	
$T_{\text{d(off)}}$	Turn-Off Delay Time ^{3,4}		---	90.8	200	
T_f	Fall Time ^{3,4}		---	21.6	40	
C_{iss}	Input Capacitance	$V_{\text{DS}}=25\text{V}$, $V_{\text{GS}}=0\text{V}$, $F=1\text{MHz}$	---	6805	10000	pF
C_{oss}	Output Capacitance		---	445	680	
C_{rss}	Reverse Transfer Capacitance		---	195	280	
R_g	Gate resistance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=0\text{V}$, $F=1\text{MHz}$	---	1.3	2.6	Ω

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	100	A
			---	---	200	A
V_{SD}	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. $V_{\text{DD}}=25\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.1\text{mH}$, $I_{\text{AS}}=95\text{A}$, Starting $T_J=25^\circ\text{C}$
3. The data tested by pulsed , pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.


Fig.1 Continuous Drain Current vs. T_C

Fig.2 Normalized RD_{SON} vs. T_J

Fig.3 Normalized V_{th} vs. T_J

Fig.4 Gate Charge Characteristics

Fig.5 Normalized Transient Impedance

Fig.6 Maximum Safe Operation Area